

**FOR ADDITIONAL INFORMATION
CONTACT:**
Phone: (518) 452-2880
E-mail: info@yincae.com



YINCAE Advanced Materials, LLC
19 Walker Way, Albany, NY 12205
www.yincae.com

FOR IMMEDIATE RELEASE

Press Release

YINCAE Showcases High-Performance Materials at IMAPS 2025

08/25/2025 (Albany, NY) — YINCAE, a global leader in advanced electronic materials, is set to showcase its latest innovations in **underfill, die attach, and liquid metal technologies** at **IMAPS, San Diego, September 30 - October 1**. Visitors will experience next-generation solutions designed to meet the reliability, thermal, and processing challenges of today's most demanding electronic applications.

Highlights at the IMAPS:

- **High-Performance Underfill (UF 120HA2):**
 - 100% compatible with no-clean flux residue
 - Passes 10×260°C reflow without cleaning
 - Low CTE for superior reliability
 - Fast flow and rapid cure for efficient assembly
- **Advanced Die Attach Materials (TM 230-2):**
 - Low-void, high-reliability solutions
 - Low-temperature process compatibility
 - Options for both soldering and sintering for large-die applications
- **Next-Generation Liquid Metal Solutions (TM 150LM):**
 - High viscosity and superior reliability
 - No blow-out or pump-out, even under thermal cycling
 - Exceptional heat dissipation for TIM1, TIM1.5, and TIM2 applications

“Our portfolio demonstrates a unique combination of **thermal performance, reliability, and process efficiency**,” said Dr. Wusheng Yin, CEO at YINCAE. “We’re excited to showcase materials that enable the future of advanced packaging and high-power devices.”

Join us at Booth #817 at the IMAPS Symposium 2025 in San Diego, CA (Sept. 30 – Oct. 1) for a live demo and to meet our team. To learn more, email us at info@yincae.com or visit www.yincae.com.

Founded in 2005 & headquartered in Albany, New York, YINCAE Advanced Materials is a leading manufacturer and supplier of adhesives and electronic materials used in the microchip & optoelectronic devices. YINCAE products provide new technologies to support manufacturing processes from wafer level, to package level, to board level and final devices while facilitating smarter and faster production and supporting green initiatives.